

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN65HVD70D	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	HVD70
SN65HVD70D.Z	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	HVD70
SN65HVD70DGS	Active	Production	VSSOP (DGS) 10	80 TUBE	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	VD70
SN65HVD70DGS.Z	Active	Production	VSSOP (DGS) 10	80 TUBE	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	VD70
SN65HVD70DGSR	Active	Production	VSSOP (DGS) 10	2500 LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	VD70
SN65HVD70DGSR.Z	Active	Production	VSSOP (DGS) 10	2500 LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	VD70
SN65HVD70DR	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	HVD70
SN65HVD70DR.Z	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	HVD70
SN65HVD70DRG4.Z	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	HVD70
SN65HVD71D	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HVD71
SN65HVD71D.Z	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HVD71
SN65HVD71DGK	Active	Production	VSSOP (DGK) 8	80 TUBE	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	VD71
SN65HVD71DGK.Z	Active	Production	VSSOP (DGK) 8	80 TUBE	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	VD71
SN65HVD71DGKR	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	VD71
SN65HVD71DGKR.Z	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	VD71
SN65HVD71DR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HVD71
SN65HVD71DR.Z	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HVD71
SN65HVD71DRG4.Z	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HVD71
SN65HVD73D	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HVD73
SN65HVD73D.Z	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HVD73
SN65HVD73DGS	Active	Production	VSSOP (DGS) 10	80 TUBE	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	VD73
SN65HVD73DGS.Z	Active	Production	VSSOP (DGS) 10	80 TUBE	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	VD73
SN65HVD73DGSR	Active	Production	VSSOP (DGS) 10	2500 LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	VD73
SN65HVD73DGSR.Z	Active	Production	VSSOP (DGS) 10	2500 LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	VD73
SN65HVD73DR	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HVD73
SN65HVD73DR.Z	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HVD73
SN65HVD74D	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HVD74
SN65HVD74D.Z	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HVD74
SN65HVD74DGK	Active	Production	VSSOP (DGK) 8	80 TUBE	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	VD74

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN65HVD74DGK.Z	Active	Production	VSSOP (DGK) 8	80 TUBE	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	VD74
SN65HVD74DGKR	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU SN NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	VD74
SN65HVD74DGKR.Z	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	VD74
SN65HVD74DR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HVD74
SN65HVD74DR.Z	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HVD74
SN65HVD74DRG4.Z	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HVD74
SN65HVD76D	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	HVD76
SN65HVD76D.Z	Active	Production	SOIC (D) 14	50 TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	HVD76
SN65HVD76DGS	Active	Production	VSSOP (DGS) 10	80 TUBE	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	VD76
SN65HVD76DGS.Z	Active	Production	VSSOP (DGS) 10	80 TUBE	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	VD76
SN65HVD76DGSR	Active	Production	VSSOP (DGS) 10	2500 LARGE T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	VD76
SN65HVD76DGSR.Z	Active	Production	VSSOP (DGS) 10	2500 LARGE T&R	Yes	NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	VD76
SN65HVD76DR	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	HVD76
SN65HVD76DR.Z	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	HVD76
SN65HVD76DRG4.Z	Active	Production	SOIC (D) 14	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	HVD76
SN65HVD77D	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HVD77
SN65HVD77D.Z	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HVD77
SN65HVD77DGK	Active	Production	VSSOP (DGK) 8	80 TUBE	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	VD77
SN65HVD77DGK.Z	Active	Production	VSSOP (DGK) 8	80 TUBE	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	VD77
SN65HVD77DGKR	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	VD77
SN65HVD77DGKR.Z	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	VD77
SN65HVD77DR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HVD77
SN65HVD77DR.Z	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HVD77
SN65HVD77DRG4.Z	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HVD77

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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